

MA27D27

Silicon epitaxial planar type

For super high speed switching

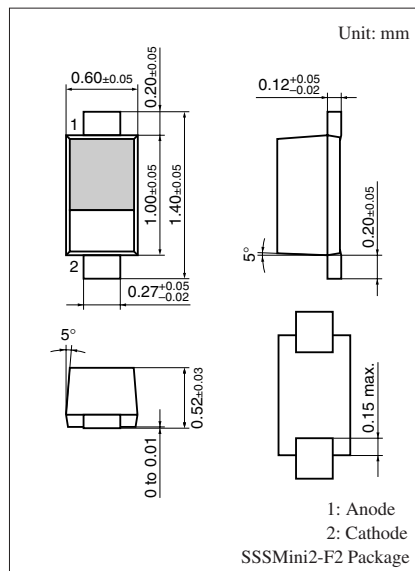
■ Features

- Small reverse current I_R
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}
- SSS-Mini type 2-pin package

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|---|-------------|-------------|------------------|
| Reverse voltage | V_R | 20 | V |
| Repetitive peak reverse voltage | V_{RRM} | 20 | V |
| Forward current (Average) | $I_{F(AV)}$ | 100 | mA |
| Peak forward current | I_{FM} | 200 | mA |
| Non-repetitive peak forward surge current * | I_{FSM} | 1 | A |
| Junction temperature | T_j | 150 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +150 | $^\circ\text{C}$ |

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



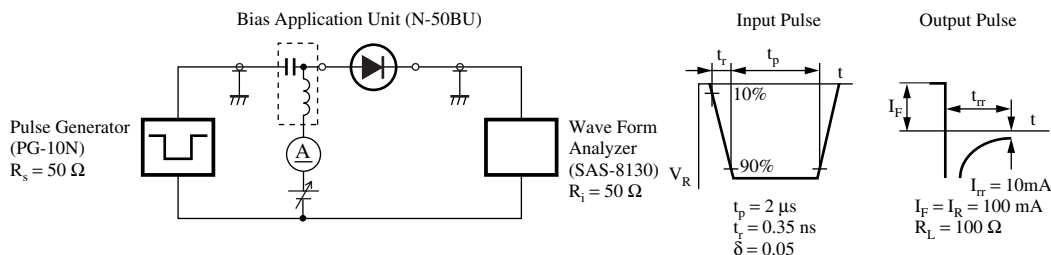
Marking Symbol: 8L

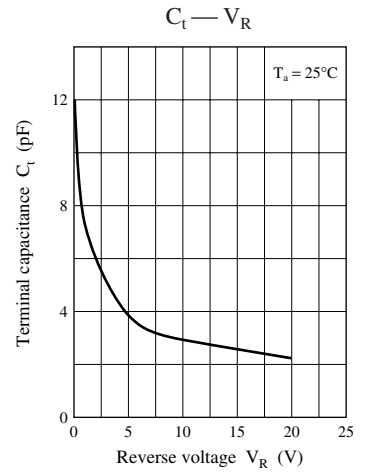
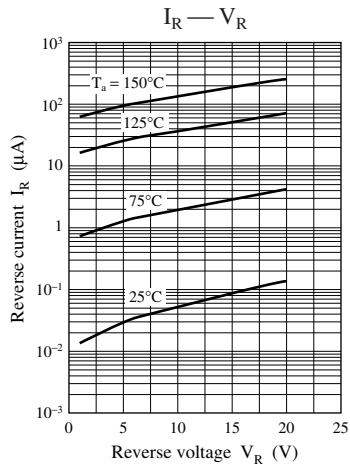
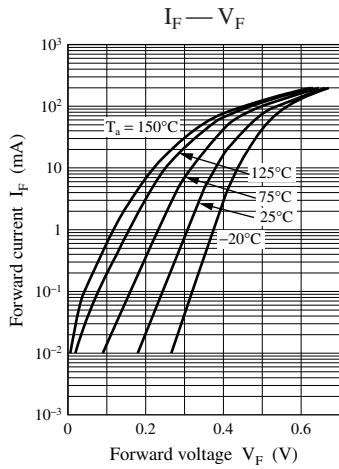
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-------------------------|----------|---|-----|------|------|---------------|
| Forward voltage | V_{F1} | $I_F = 10\text{ mA}$ | | 0.38 | 0.44 | V |
| | V_{F2} | $I_F = 100\text{ mA}$ | | 0.54 | 0.58 | |
| Reverse current | I_R | $V_R = 10\text{ V}$ | | | 0.3 | μA |
| Terminal capacitance | C_t | $V_R = 0\text{ V}, f = 1\text{ MHz}$ | | 11 | | pF |
| Reverse recovery time * | t_{rr} | $I_F = I_R = 100\text{ mA}$ $I_{rr} = 10\text{ mA}, R_L = 100\ \Omega$ | | 1 | | ns |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Rated input/output frequency: 250 MHz
4. *: t_{rr} measurement circuit





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